AN APPARATUS FOR HANDLING A SEMICONDUCTOR COMPONENT

Abstract

An apparatus for handling or transferring a semiconductor component. The apparatus comprises a first structure and a second structure coupled thereto. The first structure and the second structure define a vacuum chamber therebetween. The second structure comprises at least one module coupled thereto. Each module comprises a passageway defined therethrough. Vacuum is applied through the passageway for facilitating pick up of the semiconductor component at a first position and for securing the semiconductor component to the module during displacement of the module from the first position to a second position. The apparatus comprises a plunger. Displacement of the plunger from a retracted position to an extended position impedes fluid communication between the passageway of the module and the chamber. Displacement of the plunger to the extended position further causes purging of air through the passageway of the module to thereby detach the semiconductor component from the module. A method for transferring the semiconductor component using the apparatus is also provided by the present invention.

Figure 3